



Building the Digital Infrastructure



NEXCOM

NISE 3110 User Manual

Version 1.3

March, 2008

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Declaration of Conformity

CE

This product has passed the CE test for environmental specifications when shielded cables are used for external wiring. We recommend the use of shielded cables. Please contact your local supplier for ordering information.

This product has passed the CE test for environmental specifications. Test conditions for passing included the equipment being operated within an industrial enclosure. In order to protect the product from being damaged by ESD (Electrostatic Discharge) and EMI leakage, we strongly recommend the use of CE-compliant industrial enclosure products.

FCC Class A

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment.

This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

Installation Suggestions

Ensure you have a stable, clean working environment. Dust and dirt can get into components and cause a malfunction. Use containers to keep small components separated.

Adequate lighting and proper tools can prevent you from accidentally damaging the internal components. Most of the procedures that follow require only a few simple tools, including the following:

- A Philips screwdriver

- A flat-tipped screwdriver

- A grounding strap

- An anti-static pad

Using your fingers can disconnect most of the connections. It is recommended that you do not use needlenose pliers to disconnect connections as these can damage the soft metal or plastic parts of the connectors.

Handling Precautions

- ✘ Always disconnect the unit from the power outlet whenever you are installing or fixing a component inside the chassis.
- ✘ If possible, always wear a grounded wrist strap when you are installing or fixing a component inside the chassis. Alternatively, discharge any static electricity by touching the bare metal chassis of the unit case, or the bare metal body of any other grounded appliance.
- ✘ Hold electronic circuit boards by the edges only. Do not touch the components on the board unless it is necessary to do so. Do not flex or stress the circuit board.
- ✘ Use the correct screws and do not overly tighten them.
- ✘ Keep the original packaging and static-protective bag in case the unit has to be returned.

NEXCOM RMA Policy

1. Warranty Period

NEXCOM manufactures products that are new or equivalent to new in accordance with industry standard. NEXCOM warrants that products will be free from defect in material and workmanship for 24 months beginning on the date of invoice by NEXCOM. HCP series products (Blade Server) which are manufactured by NEXCOM are covered by a three year warranty period.

2. RMA (Return Merchandise Authorization)

- ✘ Customers shall enclose the “NEXCOM RMA Service Form” with the returned packages.
- ✘ Customers must collect all the information about the problems encountered and note anything abnormal or, print out any on-screen messages, and describe the problems on the “NEXCOM RMA Service Form” for the RMA number apply process.
- ✘ Customers can send back the faulty products with or, without accessories (manuals,cable, etc.) and any unnecessary components from the card, such as CPU and RAM.
If the components were suspected as part of the problems, please note clearly that which components are included. Otherwise, NEXCOM is not responsible for the devices/parts.
- ✘ Customers are responsible to for the safe packaging of defective products are durable enough to be resistant against further damage and deterioration during transportation. In case of damages occurred during the transportation, the repair is treated as “Out of Warranty.”

- ✘ 2.5 Any products returned by NEXCOM to other locations besides the customers' site will bear an extra charge and will be billed to the customer.

3. Repair service charges for out of warranty products

NEXCOM will charge for out of warranty products in two categories, one is basic diagnostic fee and another is component (product) fee.

System level

- ✘ Component fee: NEXCOM will only charge for main components, such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistor, capacitor.
- ✘ Items will be replaced with NEXCOM products if the original one is not able to be repaired. Ex: motherboard, power supply, etc.
- ✘ Replaced with 3rd party products if needed.
- ✘ If RMA goods can not be repaired, NEXCOM will return it to customer without any charge.

Board level

- ✘ Component fee: NEXCOM will only charge for main components, such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistors, capacitors.
- ✘ If RMA goods can not be repaired, NEXCOM will return it to customer without any charge.

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RoHS Compliance



NEXCOM RoHS Environmental Policy and Status Update. Nexcom is a global citizen for building the digital infrastructure. We are committed to providing green products and services, which are compliant with European Union RoHS (Restriction on Use of Hazardous Substance in Electronic Equipment) directive 2002/95/EU, to be your trusted green partner and to protect our environment.

RoHS restricts the use of Lead (Pb) < 0.1% or 1,000ppm, Mercury (Hg) < 0.1% or 1,000ppm, Cadmium (Cd) < 0.01% or 100ppm, Hexavalent Chromium (Cr6+) < 0.1% or 1,000ppm, Polybrominated biphenyls (PBB) < 0.1% or 1,000ppm, and Polybrominated diphenyl Ethers (PBDE) < 0.1% or 1,000ppm.

In order to meet the RoHS compliant directives, NEXCOM has established an engineering and manufacturing task force in to implement the introduction of green products. The task force will ensure that we follow the standard NEXCOM development procedure and that all the new RoHS components and new manufacturing processes maintain the highest industry quality levels for which NEXCOM are renowned.

The model selection criteria will be based on market demand. Vendors and suppliers will ensure that all designed components will be RoHS compliant.

How do you recognize NEXCOM RoHS Products?

For existing products where there are non-RoHS and RoHS versions, the suffix “(LF)” will be added to the compliant product name.

For example, PEAK 7220VL2G RoHS version will become PEAK 7220VL2G(LF).

All new product models launched after January 2006 will be RoHS compliant.

They will use the usual NEXCOM naming convention.

For example, PEAK 870VL2, NBP14570, EBC 420 etc. All RoHS compliant model and component manufacturing part numbers will be suffixed “X00”

Manual Revision History

Revision	Date	Description
1.0	Sep., 07	First Edition, V1.0
1.1	Nov. 07	Add Appendix C “power consumption”
1.2	Feb.,08	Correct P28 GPIO pin definition (J11)
1.3	March, 08	Add the Appendix E: Display Setting Modify the Appendix B: GPIO Programming guide (add the note for SPC150)



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Chapter 1 General Information

NECOM

Fan-less BOX Computer **NISE 3110**

1.1 Product Overview

Featuring Intel 945GME & ICH7 chipsets, the NISE 3110 fan-less box computer supports Intel's Core 2 Duo /Celeron M processor with 533/667 MHz FSB and DDR2 667/533 memory. The rugged NISE 3110 fan-less box computer is designed for space-critical application requires extreme reliability, low-power consumption and versatile I/O configuration. For added flexibility, the NISE 3110 also boasts three RS232 ports, one RS232/422/485 port and one PCI expansion slot.

For data storage, the NISE 3110 provides one CompactFlash socket and one 2.5" HDD drive bay. The System supports ATX mode power feature and can accept a wide range of power supplies from 12 V DC to 30 V DC.

Housed in a compact 195 mm x 268 mm x 80 mm heavy-duty aluminum chassis, the NISE 3110 is designed for reliable, maintenance-free industrial computing. The NISE 3110 fan-less box computer offers a cost-effective solution for a multitude of mission-critical embedded computing applications in automation, machine control, and POS systems.

- ✘ Support Intel® Core 2 Duo / Core Duo/ Celeron® M processors
- ✘ Intel® 945GME Chipsets
- ✘ Dual 1000/100/10Mbps LAN ports
- ✘ 6 x USB2.0/ VGA / DVI/ 4 x SIO
- ✘ One PCI Expansion Slot

1.2 Block Diagram

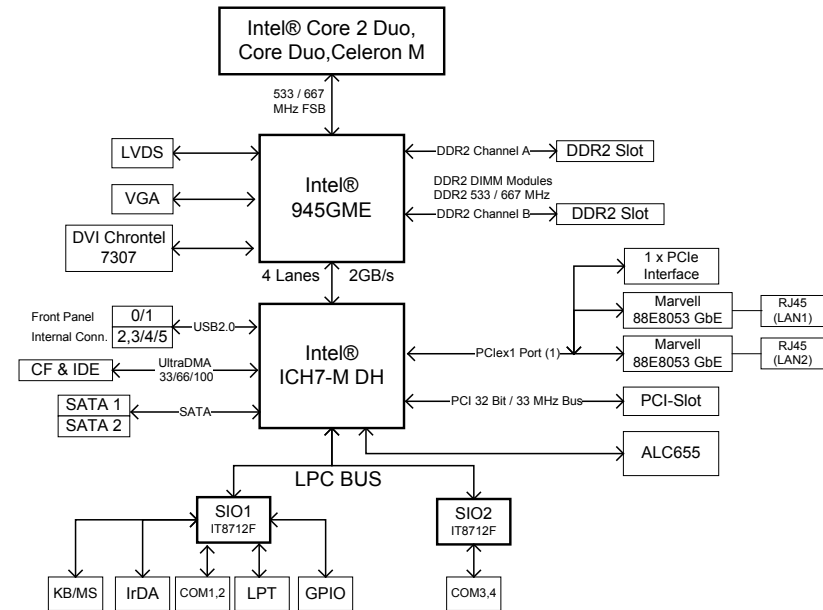


Figure 1.1 : Block Diagram of EBC 576

1.3 Specifications

Main Board

- ✘ EBC 576
- ✘ Support Intel® Core 2 Duo, Core Duo, Celeron® M family processors with 533/667 MHz
- ✘ Intel® Embedded Processor Reference List (Intel® Longevity CPU):
 - Core Duo Processor (T2300E) 1.66 G
 - Core Duo Processor (T2500) 2.0G
 - Celeron® M 530 1.73G
 - Celeron® M 440 1.86G

Chipset

- ✘ Intel® 945GME Graphics Memory Controller Hub (GMCH)
- ✘ Intel® 82801 GBM ICH7 Mobile digital Home (ICH7-M)

Main Memory

- ✘ 2 x 240 pin DDR2 533/667 DIMM sockets, up to 2 GB unbuffered non-ECC DDR SDRAM (Max. 3G Capacity supported)

Expansion Slot

- ✘ Supports one 32-bit/ 33MHz PCI card
- ✘ PCI Length support:
 - 160 mm (When 2.5" HDD installed)
 - 240 mm (When no HDD is installed)

I/O Interface-Front

- ✘ Customized logo(Optional)
- ✘ HDD Access/Power/LAN status LEDs
- ✘ 2 x USB 2.0 ports
- ✘ ATX power on/off switch

I/O Interface-Rear

- ✘ 2 x PS/2 connectors (KB/MS)
- ✘ 1 x VGA connector
- ✘ 4 x USB 2.0 ports
- ✘ 2 x GbE LAN Ports
- ✘ 4 x Serial Ports, with 1x DB44 connector (Three ports support RS232, One port supports RS232/422/485)
- ✘ 1 x DVI interface
- ✘ 1 x Mic-in and 1 x Speaker-out
- ✘ 1 x 2-pin connector output for remote power on/off switch
- ✘ DC-in power connector for +12V ~+30V DC power input

Device

- ✘ 1 x On-board CompactFlash socket
- ✘ 1 x Internal 2.5" HDD drive bay

Power Input

- ✘ DC to DC power designed for on-board support of 12 to 30 VDC
(Max: 120 Watts)
- ✘ 1 x External 120 W AC adapter
Power input: 100 to 240 V AC 2 A 50/60 Hz
Power output: 19 VDC

Dimensions

- ✘ 195 mm (W) x 268 mm (D) x 80 mm (H) (7.6" x 10.5" x 3.1")

Construction

- ✘ Aluminum chassis with fan-less design

Environment

- ✘ Operating temperature:
Ambient with air flow : 0°C to 40°C (CPU loading: 70% less continently)
- ✘ NISE 3110 Tcase (Surface Temperature of Chassis)
5°C to 50°C (W/HDD)
-10°C to 55°C (W/CF card only)
- ✘ Storage temperature: -20°C to 80°C
Relative humidity: 10% to 90% (Non-condensing)

Certifications

- ✘ CE approval
- ✘ FCC

1.4 Ordering Information

Barebone

NISE 3110 (P/N: 10J0031100X0) RoHS Compliant

Intel® Core 2 Duo, Core Duo, Celeron® M Fanless Bare-Bone System, with one PCI expansion slot

1.5 Packing Materials Checklist

Description	Q'ty
Power Adapter 120W	1
Power Connector 2P	1
COM cable (1 x 44 pin connector to 4 x DB9 ports)	1
IDE Cable	1
EBC 576 CD Driver	1
EBC 576 Quick Reference Guide	1
Silicone Heatsink Compound	1

1.6 Board Layout

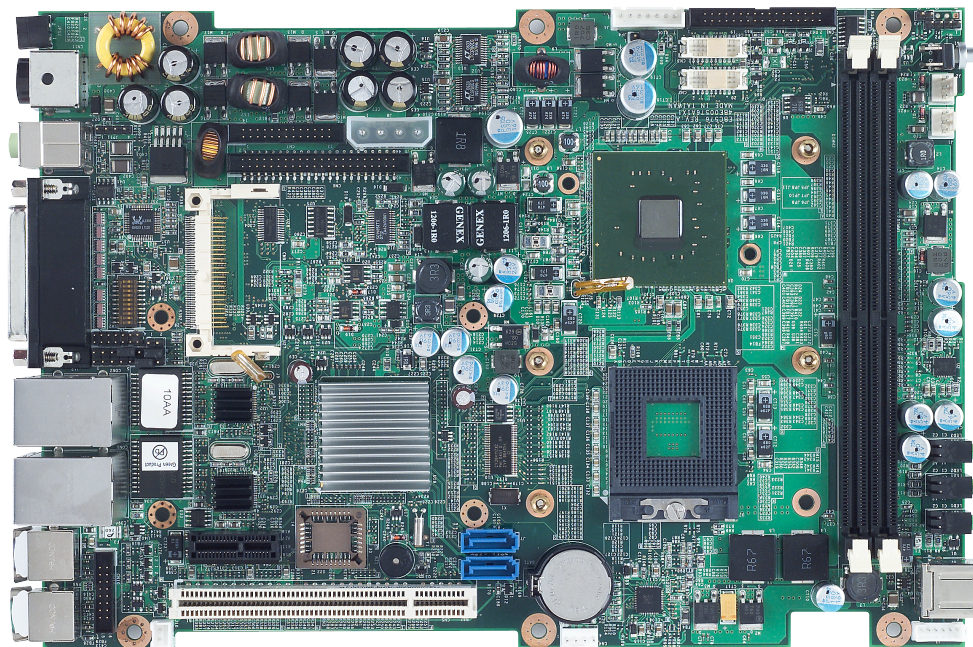


Figure 1.2 Top View of the EBC 576

1.7 Dimension Drawing

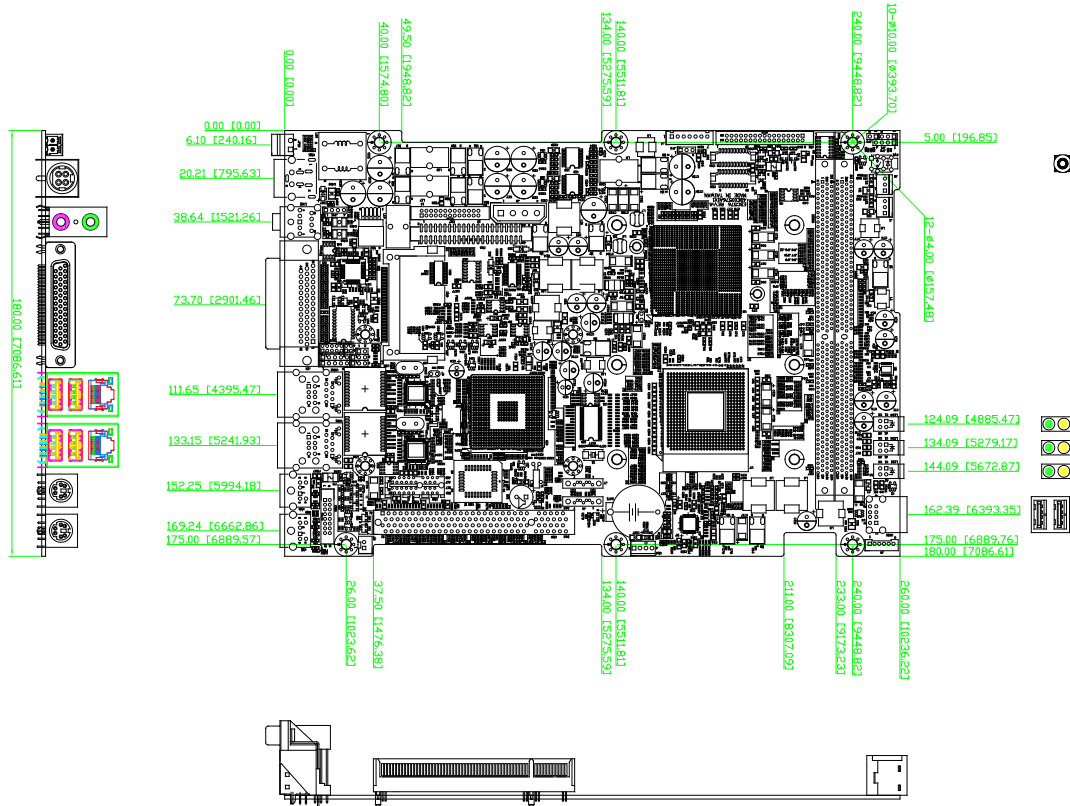


Figure 1.3: Dimension drawing of EBC 576

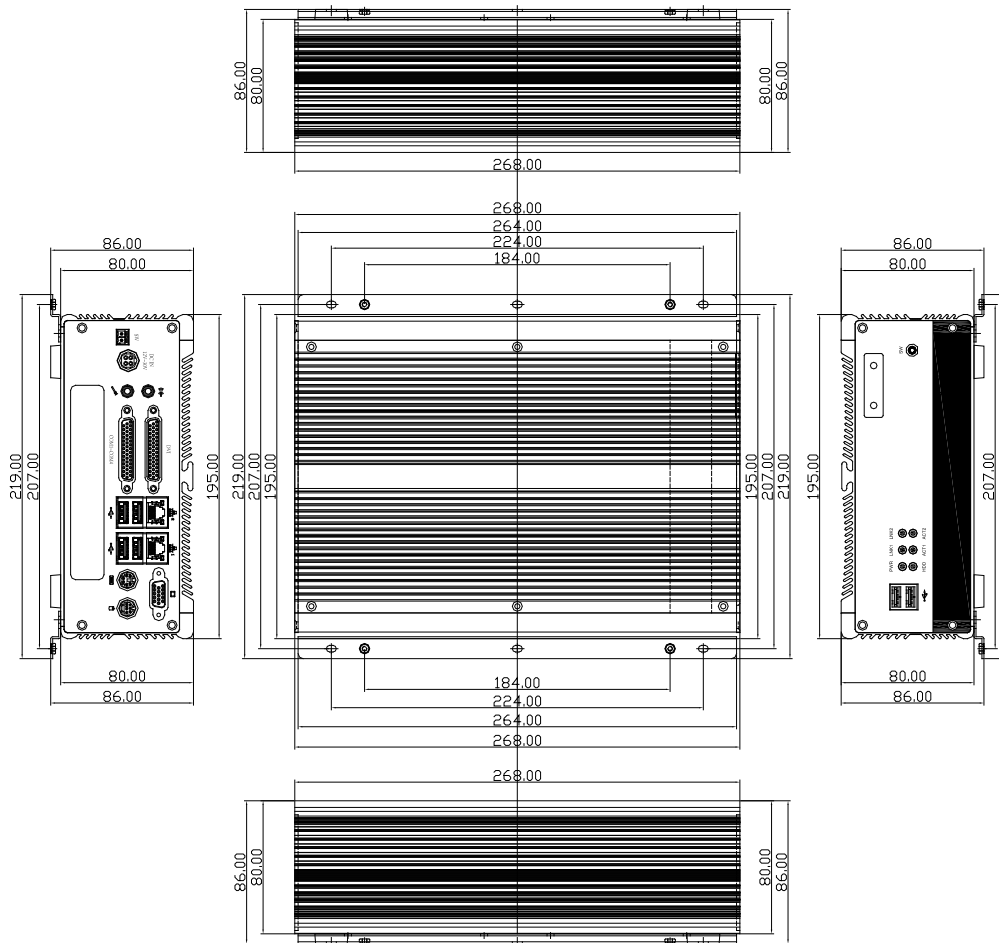


Figure 1.4 Dimension drawing of NISE 3110

Chapter 2 Jumper Setting

NECOM

Fan-less BOX Computer **NISE 3110**

2.1 Setting Jumpers

A jumper is the simplest kind of electric switch. It consists of two metal pins and a cap. When setting the jumpers, ensure that the jumper caps are placed on the correct pins. When the jumper cap is placed on both pins, the jumper is SHORT. If you remove the jumper cap, or place the jumper cap on just one pin, the jumper is OPEN. Please see the following illustrations

The illustrations on the right show a 2-pin jumper. When the jumper cap is placed on both pins, the jumper is SHORT. If you remove the jumper cap, or place the jumper cap on just one pin, the jumper is OPEN.		
	Open (Off)	Short (On)
These illustrations show a 3-pin Jumper. Pins 1 and 2 are SHORT.		

Table 2.1 Setting Jumpers

2.2 PCI Device interrupt and BUS Assignments

	Configuration BUS/DEVIC/FUNCTION	PCI INT#	REQ# /GNT#
PCI Slot1	1 / 17 / 0 1 / 18 / 0	A,B,C,D D,A,B,C	0,1

2.3 Location of Jumpers

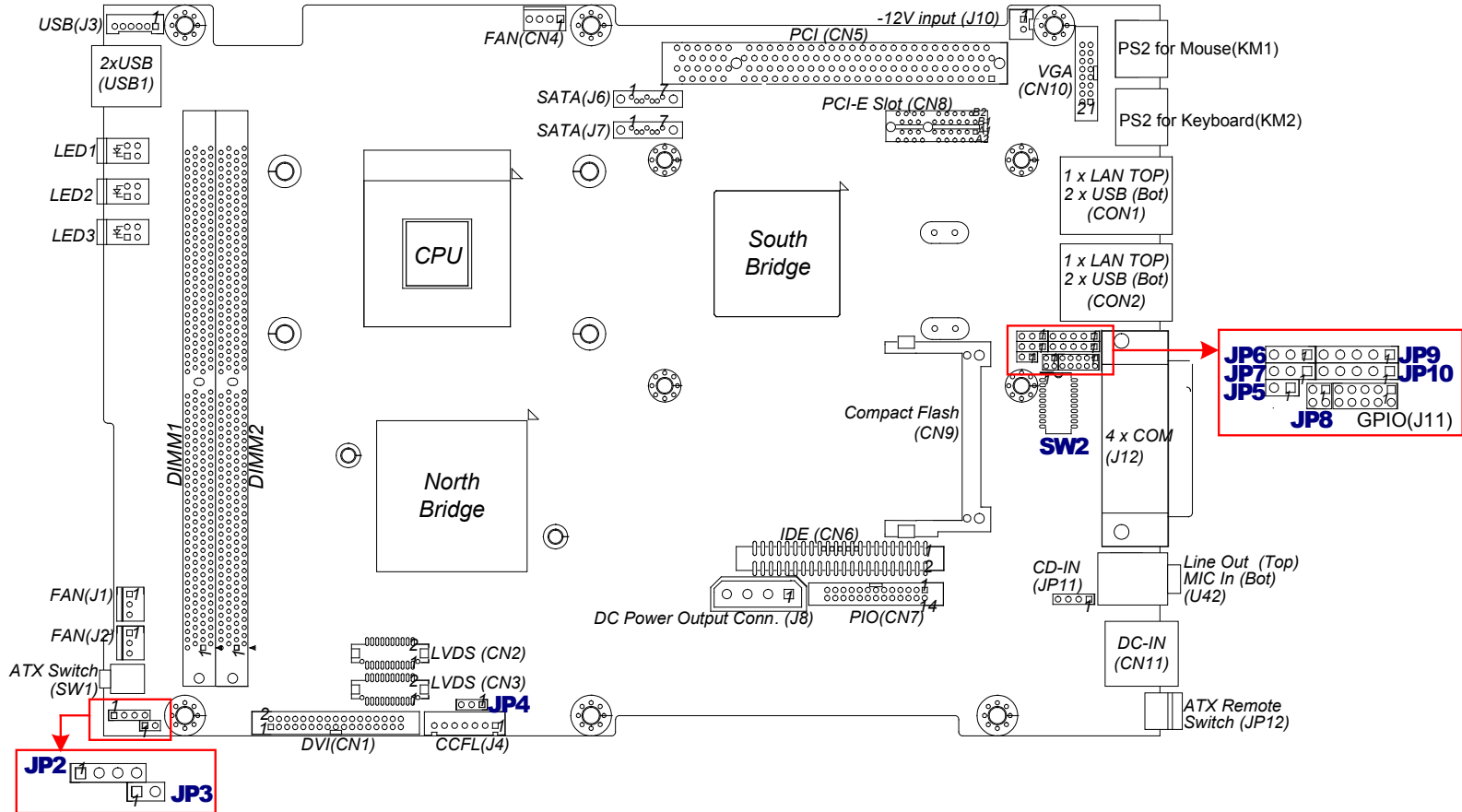
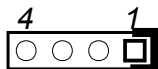


Figure 2-1: Jumper Location of EBC 576

2.4 Definition of Jumpers

✧ JP2: ATX power Switch (1x4 pin header,2.54mm)



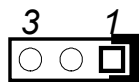
PIN	Def.	PIN	Def.	PIN	Def.
1	ATX Power on	2	ATX Power on	3-4	GND

✧ JP3: Hardware Reset (1x2 pin header,2.54mm)



PIN	Def.	PIN	Def.
1	Reset	2	GND

✧ JP4:Panel Power Select (1x3 pin header,2.54mm)



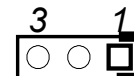
PIN	Def.
1	VCC5
2	Panel Power
3	VCC3

✧ JP5: I²C (1x2 pin header,2.54mm)



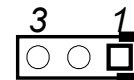
Pin	Def.	Pin	Def.
2	Data	1	CLK

✧ JP6: CMOS Status Select (1x3 pin header,2.54mm)



Pin	Status	Function
1-2	Short*	Normal Operation
2-3	Short	Clear CMOS DATA

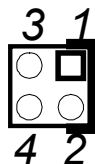
✧ JP7: CF Master / Slave Selection (1x3 pin header,2.54mm)



<1-2 pin short= Master / **2-3 pin short= Slave>

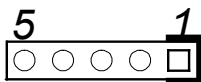
PIN	Def.	PIN	Def.	PIN	Def.
3	Slave (GND)	2	CF_CSEL	1	Master (VCC5)

✘ JP8: GPI/O Programming LED (2x2 pin header,2.0mm)



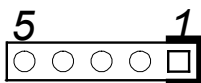
Pin	Def.	Pin	Def.
3	GP21	1	GP20
4	GND	2	GND

✘ JP9: IR Interface (1x5 pin header,2.54mm)



PIN	Def.	PIN	Def.	PIN	Def.	PIN	Def.	PIN	Def.
5	IRTX	4	GND	3	IRRX	2	CIRRX	1	VCC5

✘ JP10: RI# Signal Power Select (1x5 pin header,2.54mm)



<1-2 short: RI Power = 5v / 3-4 short: RI Power=12V / **4-5 short: Normal >

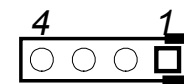
PIN	Def.	PIN	Def.	PIN	Def.	PIN	Def.	PIN	Def.
5	SP_RI2	4	RI2	3	+12V	2	RI2	1	VCC5

✘ SW2: COM2 RS232/422/485 Select (2x10 DIP SWITCH)



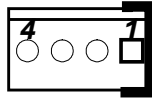
Mode	1	2	3	4	5	6	7	8	9	10
RS232*	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF
RS422	OFF	OFF	ON	OFF	ON	OFF	ON	ON	ON	ON
RS485	ON	ON	OFF	ON	ON	OFF	OFF	OFF	OFF	ON

✘ JP11: CD-IN (1x4 pin header, 2.54mm)



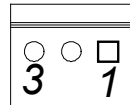
Pin.	Def.
1	CD-IN-L
2	AUDIO GND PWR
3	AUDIO GND PWR
4	CD-IN-R

✘ CN4:CPU FAN (1x4 pinWafer, 2.54mm)



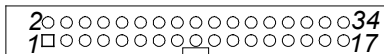
Pin.	Def.
1	GND
2	+12V
3	SENSE
4	FAN_CTRL

✘ J1/J2: SYSTEM FAN (1x 3 pin Wafer, 2.54mm)



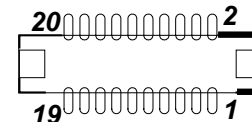
Pin.	Def.
1	GND
2	12V
3	SENSE

✧ CN1: DVI Interface (2x17 pin box header, 2.0mm)



Pin.	Def.	Pin.	Def.
1	CAS_GND	18	HPDET
2	CAS_GND	19	DVI_DATA0#
3	DVI_DATA2#	20	DVI_DATA0
4	DVI_DATA2	21	CAS_GND
5	GND	22	NC
6	NC	23	NC
7	NC	24	GND
8	DDC_CLK	25	TLC
9	DDC_DATA	26	TLC#
10	NC	27	GND
11	DVI_DATA1#	28	GND
12	DVI_DATA1	29	NC
13	CAS_GND	30	NC
14	NC	31	NC
15	NC	32	CAS_GND
16	DVI_VCC	33	CAS_GND
17	CAS_GND	34	NC

✧ CN2/CN3: LVDS Connector (2x10 pin DF13)

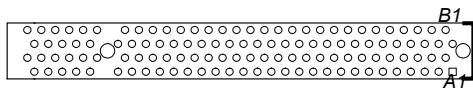


CN2			
Pin.	Def.	Pin.	Def.
1	DDCCLK	11	LA_CLK_P
2	DDC_DATA	12	LA_DATAN1
3	VDD	13	LA_CLK_N
4	LA_DATAP0	14	GND
5	NC	15	GND
6	LA_DATAN0	16	BACKLIGHT
7	NC	17	LA_DATAP2
8	VDD	18	BACKLIGHT
9	GND	19	LA_DATAN2
10	LA_DATAP1	20	GND

CN3			
Pin.	Def.	Pin.	Def.
1	DDCCLK	11	LB_CLK_P
2	DDC_DATA	12	LB_DATAN1
3	VDD	13	LB_CLK_N
4	LB_DATAP0	14	GND
5	NC	15	GND

6	LB_DATAN0	16	BACKLIGHT
7	NC	17	LB_DATAP2
8	VDD	18	BACKLIGHT
9	GND	19	LB_DATAN2
10	LB_DATAP1	20	GND

✕ CN5: PCI-SLOT (Standard PCI 32 Bit Connector)

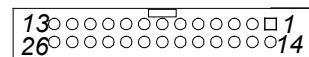


Pin.	Def. (Side B)	Def. (Side A)
1	-12V	GND
2	GND	+12V
3	GND	+5V
4	NC	+5V
5	+5V	+5V
6	+5V	Interrupt A#
7	Interrupt B#	Interrupt C#
8	Interrupt D#	+5V
9	Connector capacitance 10pf to Ground	NC
10	Request#1	+5V
11	Connector capacitance 10pf to Ground	NC
12	GND	GND
13	GND	GND
14	Clock1	Grant#1
15	GND	Reset#

16	Clock0	+5V
17	GND	Grant#0
18	Request#0	GND
19	+5V	Power Management Event#
20	Address and Data 31	Address and Data 30
21	Address and Data 29	+3.3V
22	GND	Address and Data 28
23	Address and Data 27	Address and Data 26
24	Address and Data 25	GND
25	+3.3V	Address and Data 24
26	Command & Byte Enable#3	Initialization Device Select
27	Address and Data 23	+3.3V
28	GND	Address and Data 22
29	Address and Data 21	Address and Data 20
30	Address and Data 19	GND
31	+3.3V	Address and Data 18
32	Address and Data 17	Address and Data 16
33	Command & Byte Enable#2	+3.3V
34	GND	Frame#
35	Initiator Ready#	GND
36	+3.3V	Target Ready#
37	Device Select#	Device Select#
38	GND	GND
39	Lock#	Lock#
40	Parity Error#	Parity Error#

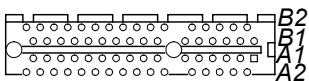
41	+3.3V	+3.3V
42	System Error#	System Error#
43	+3.3V	+3.3V
44	Command & Byte Enable#1	Command & Byte Enable#1
45	Address and Data 14	Address and Data 14
46	GND	GND
47	Address and Data 12	Address and Data 12
48	Address and Data 10	Address and Data 10
49	GND	GND
50	Connector Key	Connector Key
51	Connector Key	Connector Key
52	Address and Data 8	Address and Data 8
53	Address and Data 7	Address and Data 7
54	+3.3V	+3.3V
55	Address and Data 5	Address and Data 5
56	Address and Data 3	Address and Data 3
57	GND	GND
58	Address and Data 1	Address and Data 1
59	+5V	+5V
60	+5V	+5V
61	+5V	+5V
62	+5V	+5V

✧ CN7: Parallel port (2x13 pin box header)



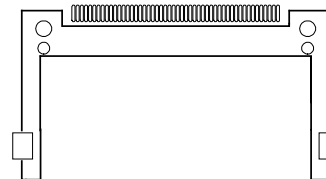
Pin.	Def.	Pin.	Def.
1	STB#	14	AFD-
2	PD0	15	ERR-
3	PD1	16	INIT-
4	PD2	17	NC
5	PD3	18	GND
6	PD4	19	GND
7	PD5	20	GND
8	PD6	21	GND
9	PD7	22	GND
10	ACK-	23	GND
11	BUSY	24	GND
12	PE	25	GND
13	SLCT	26	NC

✘ CN8: PCI-E Slot



Pin.	Def. (Side B)	Def. (Side A)
1	+12 volt power	NC
2	+12 volt power	+12 volt power
3	Reserved	+12 volt power
4	Ground	Ground
5	SMBus clock	NC
6	SMBus data	NC
7	Ground	NC
8	+3.3 volt power	NC
9	NC	3.3v volt power
10	3.3VSB	3.3v volt power
11	WAKE#	PE_RESEET#
12	Reserved	Ground
13	Ground	REFCLK_P
14	TXP0	REFCLK_N
15	TXN0	Ground
16	Ground	RXP0
17	SDVO_CTRLCLK	RXN0
18	Ground	Ground

✘ CN9: Compact Flash Socket (Type 2)

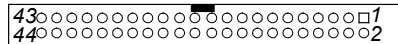


Pin.	Def.	Pin.	Def.
1	GND	2	SDD3A
3	SDD4A	4	SDD5A
5	SDD6A	6	SDD7A
7	SDCS#1	8	GND
9	GND	10	GND
11	GND	12	GND
13	VCC	14	GND
15	GND	16	GND
17	GND	18	SDA2A
19	SDA1A	20	SDA0A
21	SDD0A	22	SDD1A
23	SDD2A	24	NC
25	CF_CD2#	26	CF_CD1#
27	SDD11A	28	SDD12A
29	SDD13A	30	SDD14A
31	SDD15A	32	SDCS#3
33	NC	34	SDIOR#
35	SDIOW#	36	VCC

37	HDIRQ14	38	VCC
39	CF_SEL#	40	NC
41	IDERST#	42	SIORDY
43	SDREQ	44	SDDACK#
45	IDEACTP#	46	DIAG#
47	SDD8A	48	SDD9A
49	SDD10A	50	GND

✧ CN12(Reverse)/ CN6 (Obverse): IDE Connectoe (2x44 pin box heade,2.0mm)

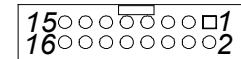
<Note: CN12 and CN6 are co-layout>



Pin.	Def.	Pin.	Def.
1	RESET	2	GND
3	DD7	4	DD8
5	DD6	6	DD9
7	DD5	8	DD10
9	DD4	10	DD11
11	DD3	12	DD12
13	DD2	14	DD13
15	DD1	16	DD14
17	DD0	18	DD15
19	GND	20	NC
21	REQ	22	GND
23	IOW	24	GND

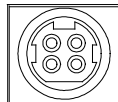
25	IOR	26	GND
27	IO_CH_RDY	28	DIAG
29	DACK#	30	GND
31	IRQ_R	32	NC
33	DA1	34	66DET
35	DA0	36	DA2
37	CS0	38	CS1
39	ACT	40	GND
41	VCC5	42	VCC5
43	GND	44	NC
41	VCC5	42	VCC5
43	GND	44	NC

✧ CN10: VGA Port (2x8 pin box header, 2.0mm)



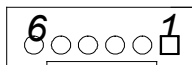
Pin.	Def.	Pin.	Def.
1	RED_VGA	9	VGA_VCC
2	GREEN_VGA	10	GND
3	BLUE_VGA	11	NC
4	NC	12	DATA_V
5	GND	13	HS_VGA
6	GND	14	VS_VGA
7	GND	15	CLK_V
8	GND	16	NC

✘ CN11: Power Jack 4 pins



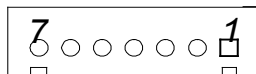
Pin	Def.	Pin	Def.
3-4	GND	1-2	DC-IN

✘ J3: Internal USB Connector (1x6 pin JST, 2.0mm)



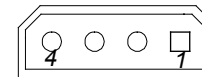
Pin.	Def.	Pin.	Def.
1	VCC	4	USB_1N
2	USB_ON	5	USB_1P
3	USB_OP	6	GND

✘ J4: CCFL (1x7 pin JST, 2.54mm)



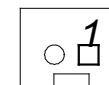
Pin.	Def.	Pin.	Def.
1	+5V	2	+12V
3	+12V	4	Brightness Ctrl
5	GND	6	GND
7	Backlight Enable		

✘ J8: DC Power output Connector (1x4-pin power jack, 5.08mm)



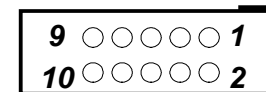
Pin.	Def.	Pin.	Def.	Pin.	Def.	Pin.	Def.
4	VCC5	3	GND	2	GND	1	+12v

✘ J10: External 12 power input connector (1x2 pin JST, 2.5mm)



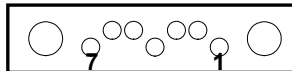
Pin.	Def.	Pin.	Def.
2	GND	1	-12V

✘ J11: External GPI/O Indicated LED (2x5 pin header, 2.0mm)



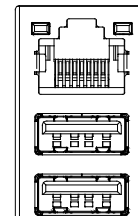
Pin.	Def.	Pin.	Def.
1	+5V	2	GND
3	GP20: Output	4	GP24: Input
5	GP21: Output	6	GP25: Input
7	GP22: Output	8	GP26: Input
9	GP23: Output	10	GP27: Input

✦ J6/J7: SATA Connector (Standard Serial ATAII 1.27mm connector)



J6			
Pin.	Def.	Pin.	Def.
1	GND	2	TXP0
4	GND	3	TXN0
7	GND	5	RXN0
		6	RXP0
J7			
Pin.	Def.	Pin.	Def.
1	GND	2	TXP1
4	GND	3	TXN1
7	GND	5	RXN1
		6	RXP1

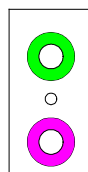
✦ CON1/ CON2: USB / LAN Port (RJ45 Jack combine with dual USB ports)



CON1-A:			
Pin.	Def.	Pin.	Def.
1	VCC	5	VCC
2	USB_2N	6	USB_3N
3	USB_2P	7	USB_3P
4	GND	8	GND
CON1-B:			
9	TX0P_E	19	VCC3
10	TX0N_E	20	LINK_E
11	TX1P_E	21	GND
12	TX2P_E	22	GND
13	TX2N_E	23	GND
14	TX1N_E	24	GND
15	TX3P_E	25	GND
16	TX3N_E	26	GND
17	ACT_E	27	GND
18	LINK_E	28	GND

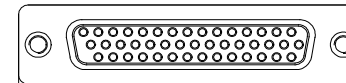
CON2-A:			
Pin.	Def.	Pin.	Def.
1	VCC	5	VCC
2	USB_4N	6	USB_5N
3	USB_4P	7	USB_5P
4	GND	8	GND
CON2-B:			
9	TX0P_F	19	VCC3
10	TX0N_F	20	LINK_F
11	TX1P_F	21	GND
12	TX2P_F	22	GND
13	TX2N_F	23	GND
14	TX1N_F	24	GND
15	TX3P_F	25	GND
16	TX3N_F	26	GND
17	ACT_F	27	GND
18	LINK_F	28	GND

✧ U42: Audio Interface (Double layer Phone jack)



	Def.		Def.
GreenUpper	Line-Out	Pink Lower	MIC-In

✧ J12: Serial Interface (COM1~COM4, 44-pin D-SUB)



COM1 (RS-232)			
Pin.	Def.	Pin.	Def.
1	DCD1	2	RXD1
3	TXD1	4	DTR1
5	GND	6	DSR1
7	RTS1	8	CTS1
9	RI1	10	GND
COM2 (RS-232)			
Pin.	Def.	Pin.	Def.
11	DCD2	12	RXD2
13	TXD2	14	DTR2
15	GND	16	DSR2
17	RTS2	18	CTS2
19	RI2	20	GND
COM3 (RS-232)			
Pin.	Def.	Pin.	Def.
21	DCD3	22	RXD3
23	TXD3	24	DTR4
25	GND	26	DSR3
27	RTS3	28	CTS3
29	RI3	30	GND

COM4 (RS-232)			
Pin.	Def.	Pin.	Def.
31	DCD4	32	RXD4
33	TXD4	34	DTR5
35	GND	36	DSR4
37	RTS4	38	CTS4
39	RI4	40	GND
41	NC	42	NC
43	NC	44	NC

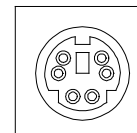
COM2 (RS-422)			
Pin.	Def.	Pin.	Def.
11	TXD#	12	TXD
13	RXD	13	RXD#
15	GND	16	RTS
17	RTS#	18	CTS
19	CTS#	20	GND

COM2 (RS-485) :pin 19 is defined as an external Power source, which can be selected for 5V or 12V by JP10

Pin.	Def.	Pin.	Def.
11	TXD#	12	TXD
	RXD#		RXD
13	Reserved	13	Reserved
15	Reserved	15	Reserved
17	Reserved	17	Reserved

19	Power Source	20	Reserved
----	--------------	----	----------

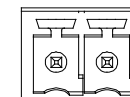
✘ KM1/ KM2 :P/S 2 Keyboard / Mouse (6-pin Mini DIMM)



KM2 For Keyboard:			
Pin.	Def.	Pin.	Def.
1	KB_DATA	2	NC
3	GND	4	KM_VCC
5	KB_CLK	6	NC

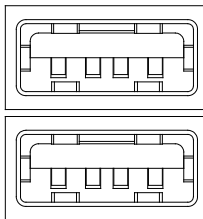
KM1 For Mouse:			
Pin.	Def.	Pin.	Def.
1	LM_DATA	2	NC
3	GND	4	KM_VCC
5	LM_CLK	6	NC

✘ JP12: ATX Remote On / Off Switch (2 pin Tterminal port, 3.81mm)



Pin.	Def.
1	GND
2	PWR_ON

✕ USB1: USB Port (Dual USB port)

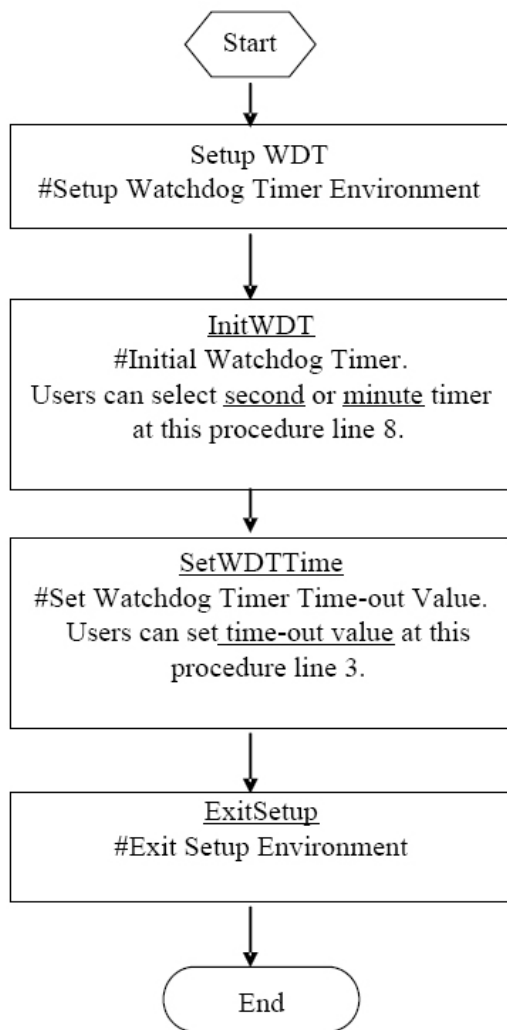


Pin.	Def.	Pin.	Def.
1	VCC	5	VCC
2	USB_1N	6	USB_ON
3	USB_1P	7	USB_OP
4	GND	8	GND

Appendix A-Watchdog Timer

NEXCOM

Fan-less BOX Computer **NISE 3110**



Watchdog Timer Common library

0	SetupWDT	PROC
1	mov	al,87h
2	out	2eh, al
3	mov	al,01h
4	out	2eh,al
5	mov	al,55h
6	out	2eh,al
7	out	2eh,al
8		
9	mov	al,07h
10	out	2eh,al
11	mov	al,07h
12	out	2fh,al
13	ret	
14	SetupWDT	ENDP

0	InitWDT	PROC
1	mov	al,71h
2	out	2eh,al
3	mov	al,30h
4	out	2fh,al
5		

6	mov	al,72h
7	out	2eh,al
8	mov	al,0c0h -Here!! set 0c0h for second, set 40h for minute
9	out	2fh,al
10	ret	
11	InitWDT	ENDP

0	SetWDTTime	PROC
1	mov	al,73h
2	out	2eh,al
3	mov	al,5-Here!! Set 5 sec. (time out vale: 0x00-0xff)
4	out	2fh,al
5	ret	
6	SetWDTTime	ENDP

0	ExitSetup	PROC
1	mov	al,02h
2	out	2eh,al
3	mov	al,02h
4	out	2fh,al
5	ret	
6	ExitSetup	ENDP

Appendix B-GPIO Programming Guide

NECOM

Fan-less BOX Computer **NISE 3110**

PIN	Description	PIN	Description
1	+5V	2	GND
3	GP20:OUTPUT	4	GP24:INPUT
5	GP21:OUTPUT	6	GP25:INPUT
7	GP22:OUTPUT	8	GP26:INPUT
9	GP23:OUTPUT	10	GP27:INPUT

IO ADDRESS : 801H

Bit0 : GP20
 Bit1 : GP21
 Bit2 : GP22
 Bit3 : GP23
 Bit4 : GP24
 Bit5 : GP25
 Bit6 : GP26
 Bit7 : GP27

Note:

- GPIO Pin-20 on EBC576/NISE3110 has been programmed for Smart Panel Computer to indicate the system power status to SPC.
- GPIO Pin-20 signal level is controlled by BIOS, high defined as system power up and low defined as system shutdown with standby power.

*If GPIO slave input port: Reflects the incoming logic levels of the pins, regardless of whether the pin is defined as an input or output. Writes to this register[bit:7..4] have no effect.

*If GPIO slave output port: Controls the levels of the GPIO output pins defined as outputs. Bit values in this register[bit:3..0] have no effect on pins defined as inputs.

Read from this register reflects the saved value last written, not the actual pin value.

Appendix C-Power Consumption

NEXCOM

Fan-less BOX Computer **NISE 3110**

DC Line 19V: (System-Only)	CPU Type: Intel Core 2 Duo T7400 2.16GHz / 06F6/C7	
	+19V	Total Watts
Full-Loading Mode	2.61A	49.59W
Idle Mode	1.12A	21.28W
Standby Mode (HDD Drive Power-Down)	1.07A	20.33W

Test Criteria:

- ✘ Test configuration should include test board, HDD drive.
- ✘ Full loading mode should utilize CPU 100% with run Burn-in test program.
- ✘ Idle mode will utilize CPU loading below 5%, and there is no data or application running.

Appendix D- Installstion Guide

NEXCOM

Fan-less BOX Computer **NISE 3110**

D.1 Handling Precautions

- ✘ Always disconnect the unit from the power outlet whenever you are installing or fixing a component inside the chassis.
- ✘ If possible, always wear a grounded wrist strap when you are installing or fixing a component inside the chassis. Alternatively, discharge any static electricity by touching the bare metal chassis of the unit case, or the bare metal body of any other grounded appliance.
- ✘ Hold electronic circuit boards (such as the EBC575 board) by the edges only. Do not touch the components on the board unless it is necessary to do so. Do not flex or stress the circuit board.
- ✘ Use the correct screws and do not overly tighten them.
- ✘ Keep the original packaging and static-protective bag in case the unit has to be returned.

D.2 Packing List

Accessories

- ✘ Quick Reference Guide x 1
- ✘ COM Port Cable x 1
- ✘ 2-pin Phoenix power connector x1
- ✘ CD Driver x 1
- ✘ 120W Power Adapter x 1
- ✘ IDE cable x 1

D.3 Installation

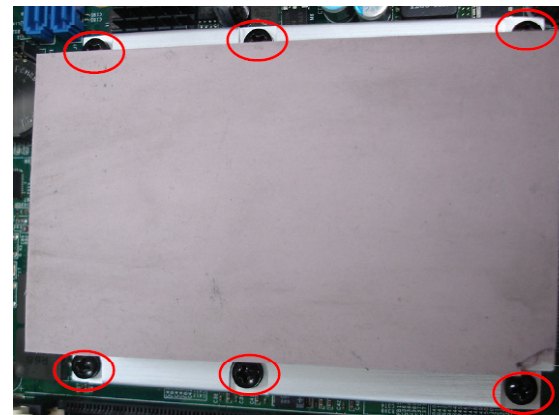
1. Open Top Cover



- ✘ Step 1-1: Remove 6 screws from the top.

2. Install/Remove CPU

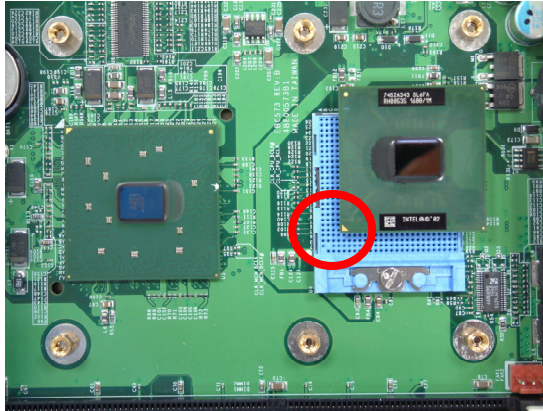
- ✘ Step 2-1: Unscrew 6 screws on heat sink



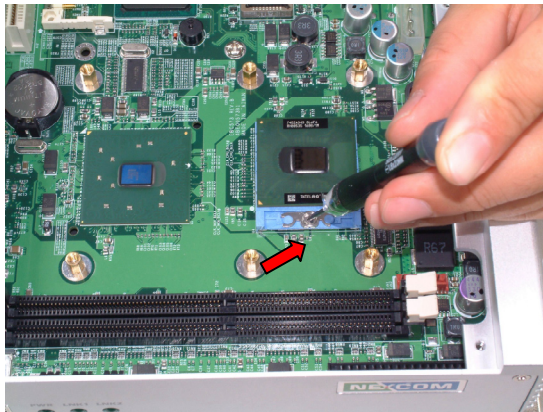
- ✘ Step 2-2: Pay attentions to CPU installation



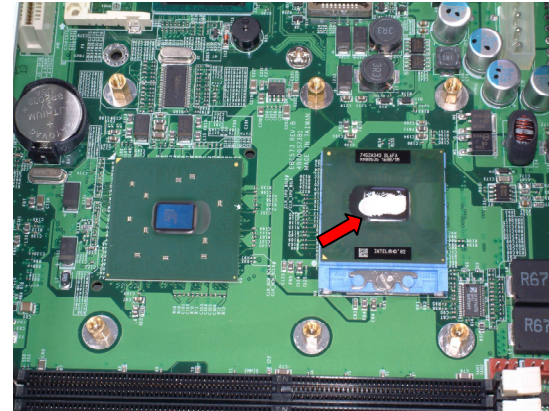
- ✘ Step 2.3: Be aware that the beveled corner of the CPU as shown in the picture is aligned to the direction of the socket.



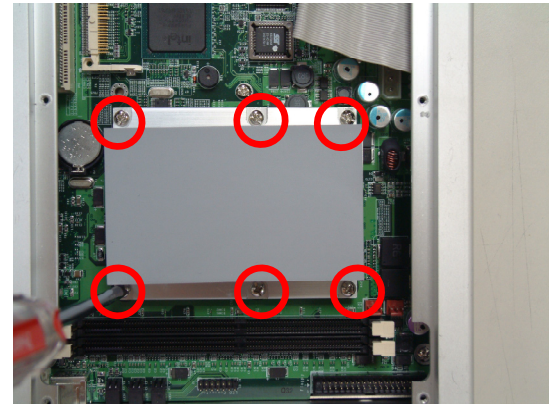
- ✘ Step 2.4: Secure the CPU



- ✘ Step 2.5: Insert heat sink silicon compound



- ✘ Step 2.6: Lock the heat sink



3. Install/Remove RAM module



✘ Step 3-1: Insert either 1 or 2 DDR

4. Close Top Cover



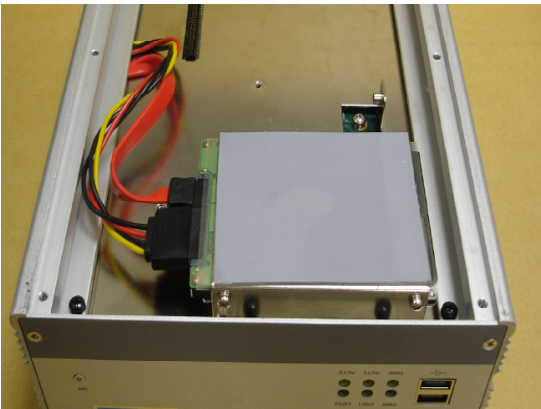
✘ Step 4-1: Secure the top cover with screws

5. Open Bottom Cover

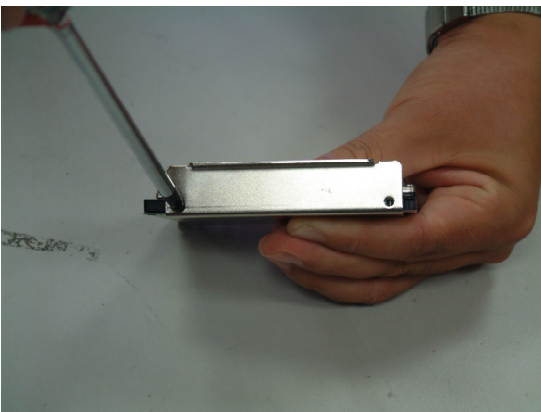


✘ Step 5-1: Remove the screws on the bottom side

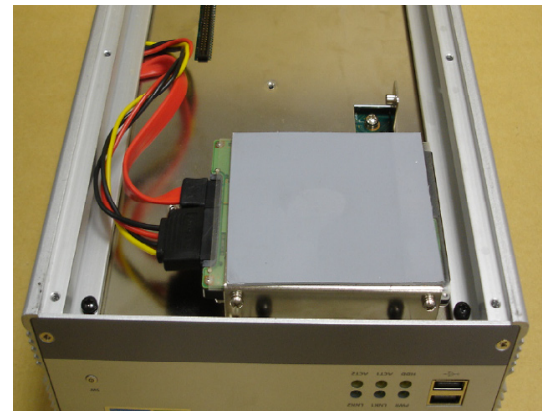
6. Install HDD



- ✘ Step 6-1: Unscrew HDD stand



- ✘ Step 6-2: Secure 2.5" HDD



- ✘ Step 6-3: Place finished stand with HDD back to the chassis and make sure it is properly secured. Plug HDD cable and pay attention to SATA power cable and SATA cable at the right position.

7. Close Bottom Cover



- ✘ Step 7-1: Lock bottom cover with screws

Appendix E- Display Setting

NEXCOM

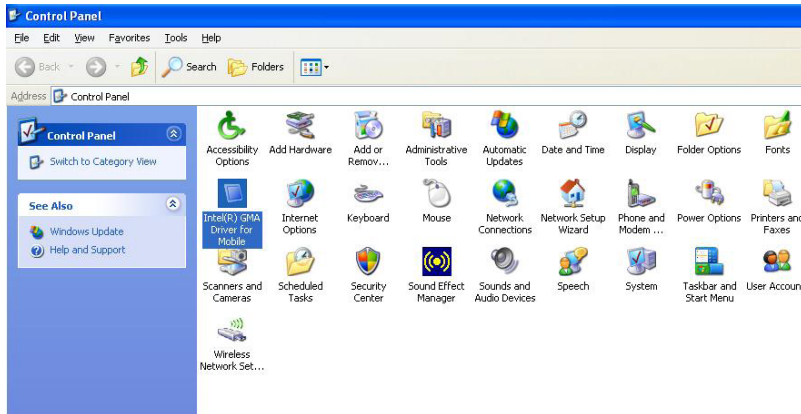
Fan-less BOX Computer **NISE 3110**

Since the chipset belongs to Intel mobile group, LVDS is the default of display. Once VGA port is not linked with monitor when power on the NISE system, LVDS will be the first display automatically afterwards. Follow below steps to select the VGA/DVI monitor as the default display for your need.

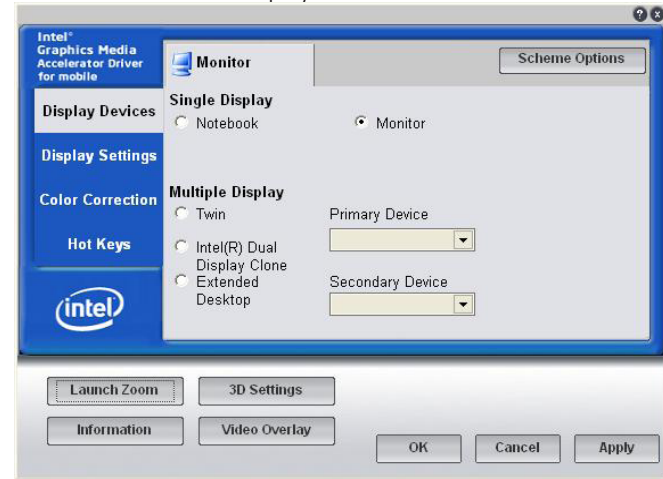
After setting, press "CTRL + ALT + F1" to enable monitor as the main display if have the same situation.

✘ Have NISE system linked with VGA/DVI monitor

✘ Select "Intel GMA Driver for Mobile" from Control Panel



✘ Select "Monitor" from Display Devices



✘ Select "Enable Hot Keys" from Hot Keys

